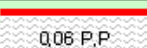
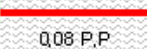








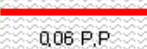



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Layer	Lay-Up Structure	Base Cu	Plat.	Expected Thick.(μm)	Imped. Structure	Pattern Wide(μm)	Pattern Space(μm)	Distance with GND	Target Value	Er	Pattern Wide(μm)	Pattern Space(μm)	Distance with GND	Target Value
1		1/3 Oz	Plated	38,0 μm 67,9 μm	SINGLE	95,0			50 Ω	DIFF	145,0	120,0		72 Ω
2		1/3 Oz	Plated	38,0 μm 74,0 μm	PLANE					PLANE				
3		1 Oz	Plated	38,0 μm 150,0 μm	SINGLE	75,0			47 Ω	DIFF	105,0	120,0		72 Ω
4		1 Oz		31,0 μm 114,7 μm	PLANE					PLANE				
5		1 Oz		31,0 μm 100,0 μm	PLANE					PLANE				
6		1 Oz		31,0 μm 147,8 μm										
7		1 Oz		31,0 μm 100,0 μm										
8		1 Oz		31,0 μm 114,7 μm	PLANE					PLANE				
9		1 Oz		31,0 μm 150,0 μm	PLANE					PLANE				
10		1 Oz	Plated	38,0 μm 72,1 μm	SINGLE	75,0			47 Ω	DIFF	105,0	120,0		72 Ω
11		1/3 Oz	Plated	38,0 μm 67,9 μm	PLANE					PLANE				
12		1/3 Oz	Plated	38,0 μm	SINGLE	95,0			50 Ω	DIFF	145,0	120,0		72 Ω

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Layer	Lay-Up Structure	Base Cu	Plat.	Expected Thick.(μm)	Imped. Structure	Pattern Wide(μm)	Pattern Space(μm)	Distance with GND	Target Value	Er	Pattern Wide(μm)	Pattern Space(μm)	Distance with GND	Target Value
1	0.06 P.P	1/3 Oz	Plated	38,0 μm 67,9 μm	DIFF	100.0	125.0		85 Ω	DIFF	95.0	155.0		90 Ω
2	0.08 P.P	1/3 Oz	Plated	38,0 μm 74,0 μm	PLANE					PLANE				
3	0.15T 1/1	1 Oz	Plated	38,0 μm 150,0 μm	DIFF	80.0	160.0		85 Ω	DIFF	75.0	205.0		90 Ω
4	0.10 P.P	1 Oz		31,0 μm 114,7 μm	PLANE					PLANE				
5	0.10T 1/1	1 Oz		31,0 μm 100,0 μm	PLANE					PLANE				
6	0.18 P.P	1 Oz		31,0 μm 147,8 μm										
7	0.10T 1/1	1 Oz		31,0 μm 100,0 μm										
8	0.10 P.P	1 Oz		31,0 μm 114,7 μm	PLANE					PLANE				
9	0.15T 1/1	1 Oz		31,0 μm 150,0 μm	PLANE					PLANE				
10	0.08 P.P	1 Oz	Plated	38,0 μm 72,1 μm	DIFF	80.0	160.0		85 Ω	DIFF	75.0	205.0		90 Ω
11	0.06 P.P	1/3 Oz	Plated	38,0 μm 67,9 μm	PLANE					PLANE				
12		1/3 Oz	Plated	38,0 μm	DIFF	100.0	125.0		85 Ω	DIFF	95.0	155.0		90 Ω

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Layer	Lay-Up Structure	Base Cu	Plat.	Expected Thick.(μm)	Imped. Structure	Pattern Wide(μm)	Pattern Space(μm)	Distance with GND	Target Value	Er	Pattern Wide(μm)	Pattern Space(μm)	Distance with GND	Target Value
1	Q06 P,P	1/3 Oz	Plated	38,0 μm 67,9 μm	DIFF	75,0	165,0		100 Ω					
2	Q08 P,P	1/3 Oz	Plated	38,0 μm 74,0 μm	PLANE									
3	0.15T 1/1	1 Oz	Plated	38,0 μm 150,0 μm										
4	Q10 P,P	1 Oz		31,0 μm 114,7 μm	PLANE									
5	0.10T 1/1	1 Oz		31,0 μm 100,0 μm	PLANE									
6	Q18 P,P	1 Oz		31,0 μm 147,8 μm										
7	0.10T 1/1	1 Oz		31,0 μm 100,0 μm										
8	Q10 P,P	1 Oz		31,0 μm 114,7 μm	PLANE									
9	0.15T 1/1	1 Oz		31,0 μm 150,0 μm	PLANE									
10	Q08 P,P	1 Oz	Plated	38,0 μm 72,1 μm										
11	Q06 P,P	1/3 Oz	Plated	38,0 μm 67,9 μm	PLANE									
12		1/3 Oz	Plated	38,0 μm	DIFF	75,0	165,0		100 Ω					